

What is claimed is:

1. A light emitting diode device comprising:
a circuit substrate;
an LED mounted on the circuit substrate;
5 a resin layer encapsulating the LED;
a reflection layer provided on the resin layer for
reflecting lights emitted from the LED.
2. The device according to claim 1 further
comprising a lower reflection film formed on the upper
10 surface of the circuit substrate.
3. The device according to claim 1 wherein the
reflection layer is provided for partly transmitting the
lights emitted from the LED.
4. The device according to claim 1 wherein the
15 reflection layer comprises a transparent holding plate and
an upper reflection film provided between the upper surface
of the resin layer and the underside of the holding plate.
5. The device according to claim 4 wherein the upper
reflection film is formed by a metal plating.
- 20 6. The device according to claim 4 wherein the upper
reflection film has an area smaller than an area of the resin
layer.